



## Features

- Active Mixer with Conversion Gain
- Integrated LO and IF Drivers
- Excellent Linearity
- Broadband 50  $\Omega$  Impedance on All Ports
- Low LO-RF Leakage
- Differential or Single Ended Inputs

## Applications

- AMPS/GSM/TDMA/CDMA Transmitter
- Other Digital Communication Applications
- High Performance RF Instrumentation

## Benefits

- Small and Thin 16-pin SSOP Package with Exposed Paddle
- Few External Components
- Fully ESD Protected

Electrostatic sensitive device.

Observe precautions for handling.



# High Linearity Active Transmitter Mixer for 800 MHz to 1000 MHz

## ATR0785

## Preliminary

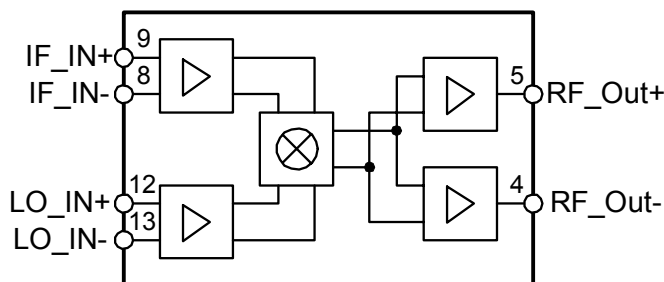
## Description

The ATR0785 is a highly linearity active mixer which is manufactured using Atmel's advanced Silicon Germanium technology for the use in a variety of high performance requiring RF systems such as digital communications.

This mixer features a frequency range of 800 MHz to 1000 MHz. It operates from a single 5 V supply and provides 14 dB of conversion gain while requiring only 0 dBm input to the integrated LO driver. An IF and an LO amplifier is also included.

The ATR0785 incorporates internal matching on each RF, IF and LO port to enhance ease of use and to reduce the external components required. The RF and LO inputs can be driven differentially or single ended.

**Figure 1.** Block Diagram

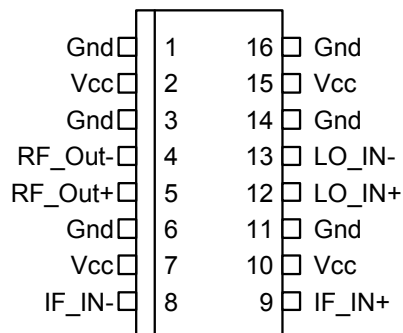


Rev. 4585B-SIGE-02/03



## Pin Configuration

**Figure 2.** Pinning TSSOP16



## Pin Description

| Pin    | Symbol  | Function                                                                                                     |
|--------|---------|--------------------------------------------------------------------------------------------------------------|
| 1      | Gnd     | Ground                                                                                                       |
| 2      | Vcc     | Supply voltage                                                                                               |
| 3      | Gnd     | Ground                                                                                                       |
| 4      | RF_OUT- | Negative RF output; nominal DC voltage is 2.3 V; (internally biased) input should be AC-coupled              |
| 5      | RF_OUT+ | Positive RF output; nominal DC voltage is 2.3 V; (internally biased) input should be AC-coupled              |
| 6      | Gnd     | Ground                                                                                                       |
| 7      | Vcc     | Supply voltage                                                                                               |
| 8      | IF_IN-  | Negative IF input; nominal DC voltage is 2.3 V, provided through off-chip inductors                          |
| 9      | IF_IN+  | Positive IF input; nominal DC voltage is 2.3 V, provided through off-chip inductors                          |
| 10     | Vcc     | Supply voltage                                                                                               |
| 11     | Gnd     | Ground                                                                                                       |
| 12     | LO_IN+  | Negative local oscillator input; nominal DC voltage is 2.3 V; (internally biased) input should be AC-coupled |
| 13     | LO_IN-  | Positive local oscillator input; nominal DC voltage is 2.3 V; (internally biased) input should be AC-coupled |
| 14     | Gnd     | Ground                                                                                                       |
| 15     | Vcc     | Supply voltage                                                                                               |
| 16     | Gnd     | Ground                                                                                                       |
| Paddle | –       | Device ground and heat sink, requires good thermal path; RF reference plane                                  |

## Absolute Maximum Ratings

| Parameters                     | Symbol         | Value        | Unit |
|--------------------------------|----------------|--------------|------|
| Supply voltages, no RF applied | $V_{CC}$       | -0.5 to +5.5 | V    |
| LO input signals               | LO_IN-; LO_IN+ | 10.0         | dBm  |
| IF input signals               | IF_IN-; IF_IN+ | 10.0         | dBm  |
| Operating case temperature     | $T_C$          | -40 to +85   | °C   |
| Storage temperature            | $T_{STG}$      | -55 to +150  | °C   |

## Thermal Resistance

| Parameters       | Symbol     | Value | Unit |
|------------------|------------|-------|------|
| Junction ambient | $R_{thJA}$ | 25    | K/W  |

## Electrical Characteristics

Test conditions: Unless otherwise noted, the following conditions apply to typical performance specification under static conditions:  $V_{CC} = +5.0$  V,  $T_{amb} = 25^\circ\text{C}$ ;  $P_{LO} = 0$  dBm; IF = 200 MHz;  $P_{IF} = -20$  dBm

| No. | Parameters                 | Test Conditions        | Pin | Symbol   | Min. | Typ. | Max. | Unit | Type* |
|-----|----------------------------|------------------------|-----|----------|------|------|------|------|-------|
|     | <b>General Performance</b> |                        |     |          |      |      |      |      |       |
|     | Supply voltage             |                        |     | $V_{CC}$ | 4.75 | 5.0  | 5.25 | V    |       |
|     | Supply current             |                        |     | $I_{CC}$ |      | 200  |      | mA   |       |
|     | LO drive                   | Matched to 50 $\Omega$ |     |          | -3   | 0    | +3   | dBm  |       |
|     | LO, IF, RF return loss     | Matched to 50 $\Omega$ |     |          |      | 14   |      | dB   |       |

Note: \*) Type means: A = 100% tested, B = 100% correlation tested, C = Characterized on samples, D = Design parameter

## RF Electrical Characteristics

Test conditions: Unless otherwise noted, the following conditions apply to typical performance specification under static conditions:  $V_{CC} = +5.0\text{ V}$ ,  $T_{amb} = 25^{\circ}\text{C}$ ;  $P_{LO} = 0\text{ dBm}$ ;  $IF = 200\text{ MHz}$ ;  $P_{IF} = -20\text{ dBm}$

| No.                         | Parameters       | Test Conditions                               | Pin | Symbol   | Min. | Typ. | Max. | Unit | Type* |
|-----------------------------|------------------|-----------------------------------------------|-----|----------|------|------|------|------|-------|
| <b>Mixer RF Performance</b> |                  |                                               |     |          |      |      |      |      |       |
|                             | RF frequency     |                                               |     | $f_{RF}$ | 800  |      | 900  | MHz  |       |
|                             | LO frequency     |                                               |     | $f_{LO}$ | 600  |      | 700  | MHz  |       |
|                             | IF frequency     |                                               |     | $f_{IF}$ | 30   | 200  | 400  | MHz  |       |
|                             | Conversion gain  |                                               |     | G        | 9    | 12   | 16   | dB   |       |
|                             | SSB noise figure |                                               |     | NF       |      | 9.0  | 11.0 | dB   |       |
|                             | Output IP3       | IF1 = IF2 =<br>-20 dBm/tone,<br>1 MHz spacing |     | OIP3     | 17   | 21   |      | dBm  |       |
|                             | Output P1dB      |                                               |     | P1dB     | 5    | 7    |      | dBm  |       |
|                             | Leakage (LO-RF)  |                                               |     |          |      | -35  | -25  | dBm  |       |
|                             | Leakage (LO-IF)  |                                               |     |          |      | -40  | -30  | dBm  |       |
| <b>Mixer RF Performance</b> |                  |                                               |     |          |      |      |      |      |       |
|                             | RF frequency     |                                               |     | $f_{RF}$ | 900  |      | 1000 | MHz  |       |
|                             | LO frequency     |                                               |     | $f_{LO}$ | 700  |      | 800  | MHz  |       |
|                             | IF frequency     |                                               |     | $f_{IF}$ | 30   | 200  | 400  | MHz  |       |
|                             | Conversion gain  |                                               |     | G        | 11   | 14   | 16   | dB   |       |
|                             | SSB noise figure |                                               |     | NF       |      | 9.0  | 11.0 | dB   |       |
|                             | Output IP3       | IF1 = IF2 =<br>-20 dBm/tone,<br>1 MHz spacing |     | OIP3     | 19   | 22   |      | dBm  |       |
|                             | Output P1dB      |                                               |     | P1dB     | 6    | 8.5  |      | dBm  |       |
|                             | Leakage (LO-RF)  |                                               |     |          |      | -30  | -20  | dBm  |       |
|                             | Leakage (LO-IF)  |                                               |     |          |      | -35  | -25  | dBm  |       |

Note: \*) Type means: A = 100% tested, B = 100% correlation tested, C = Characterized on samples, D = Design parameter

# Typical Performance

Figure 3. Conversion Gain versus Frequency + Temperature

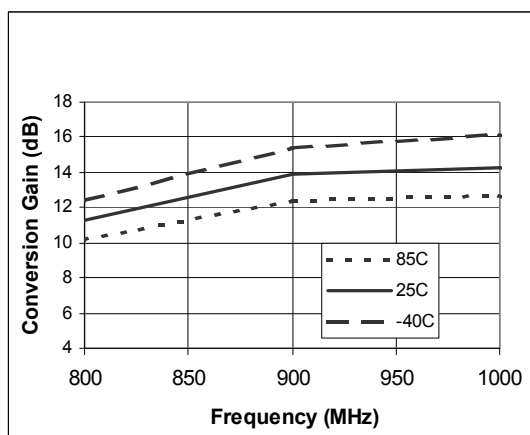


Figure 4. Output IP3 versus Frequency + Temperature

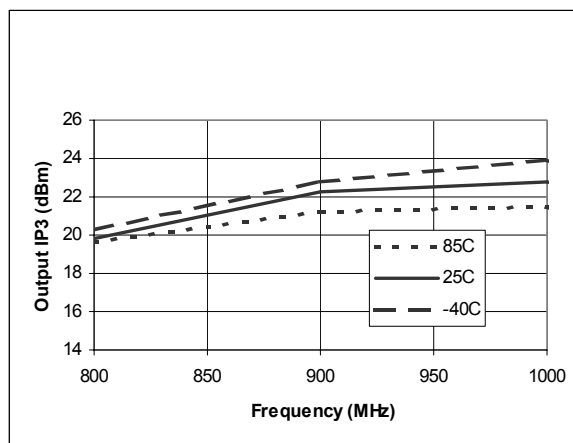
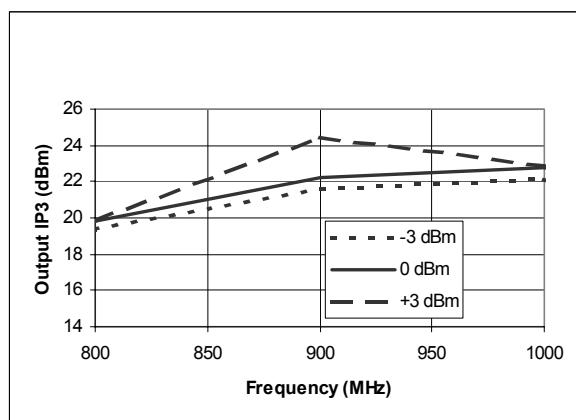
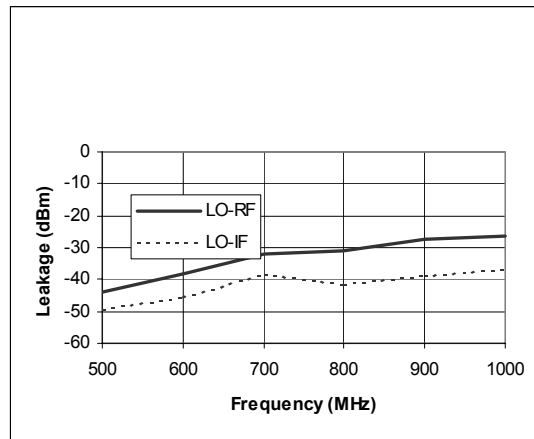


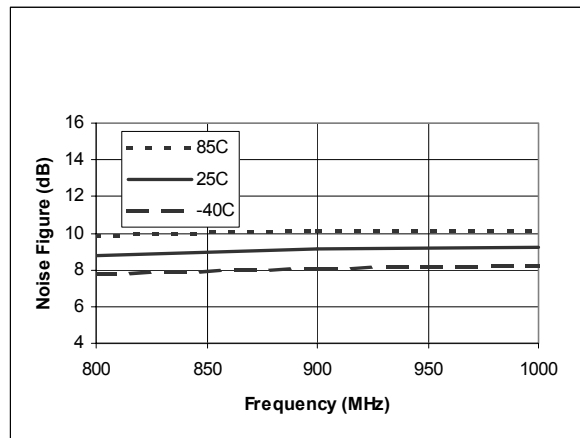
Figure 5. Output IP3 versus Frequency + LO Drive



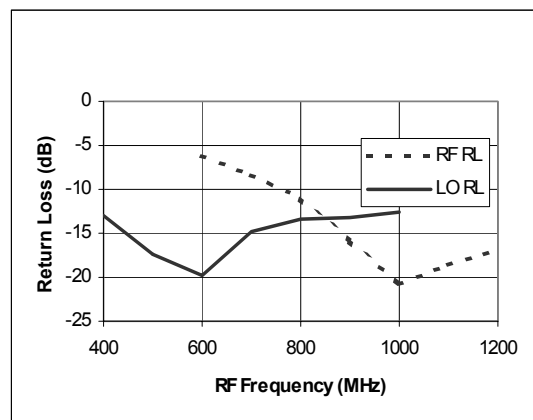
**Figure 6.** Leakages versus Frequency



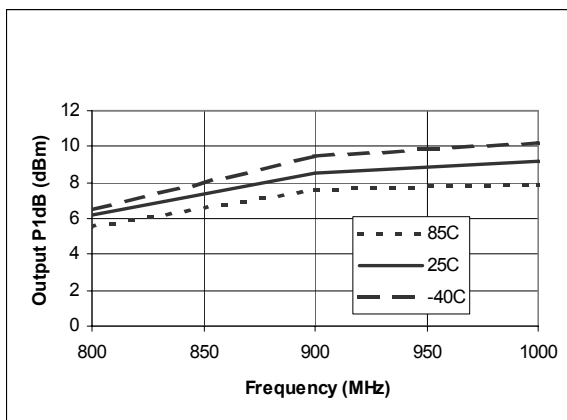
**Figure 7.** Noise Figure versus Frequency + Temperature



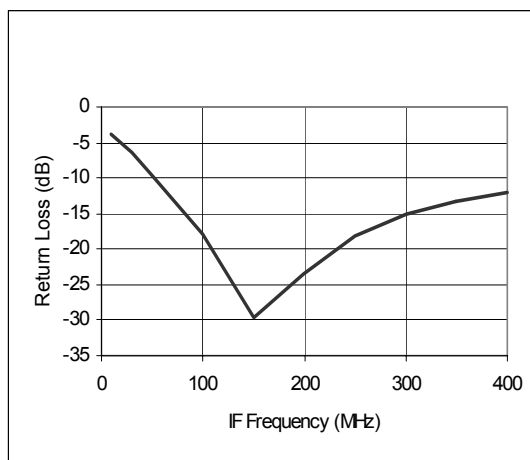
**Figure 8.** RF and LO Return Loss versus Frequency



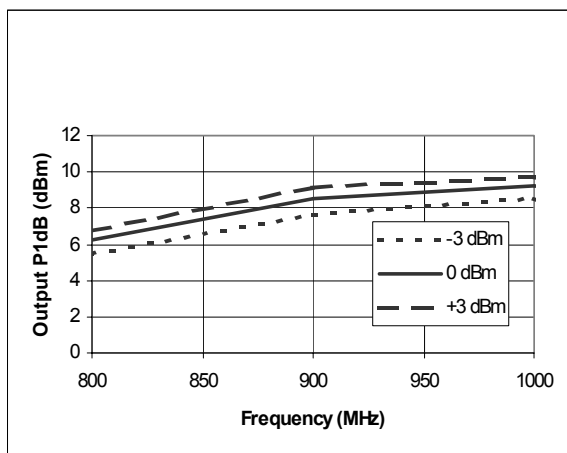
**Figure 9.** Output P1dB versus Frequency + Temperature



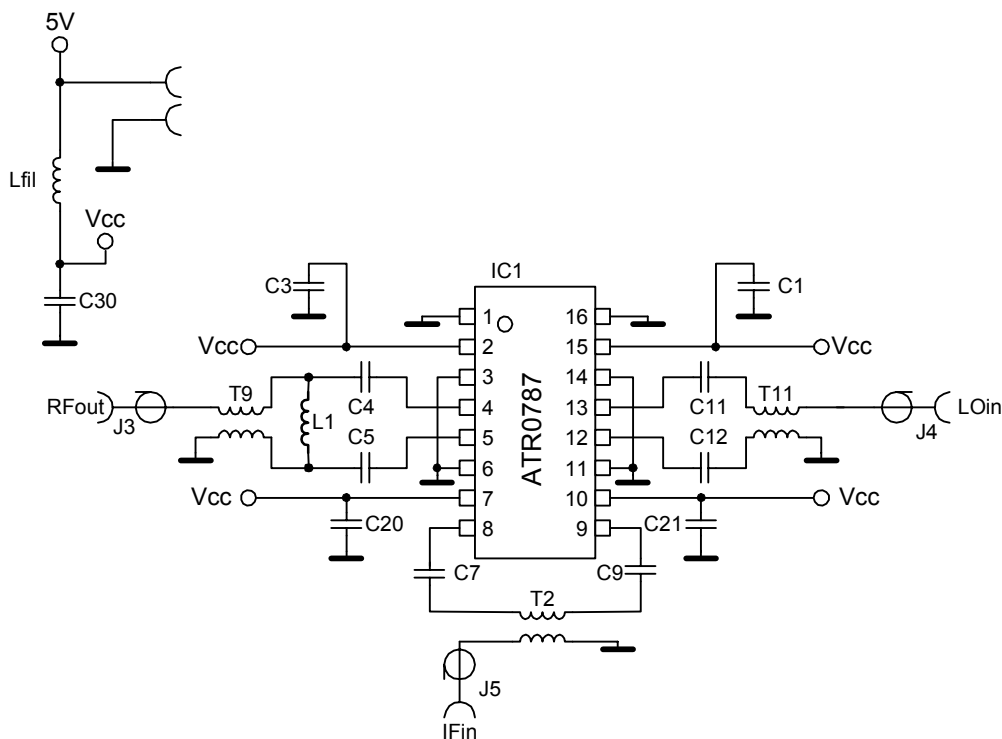
**Figure 10.** IF Return Loss versus Frequency



**Figure 11.** Output P1dB versus Frequency + LO Drive



**Figure 12. Demo Board Schematic**



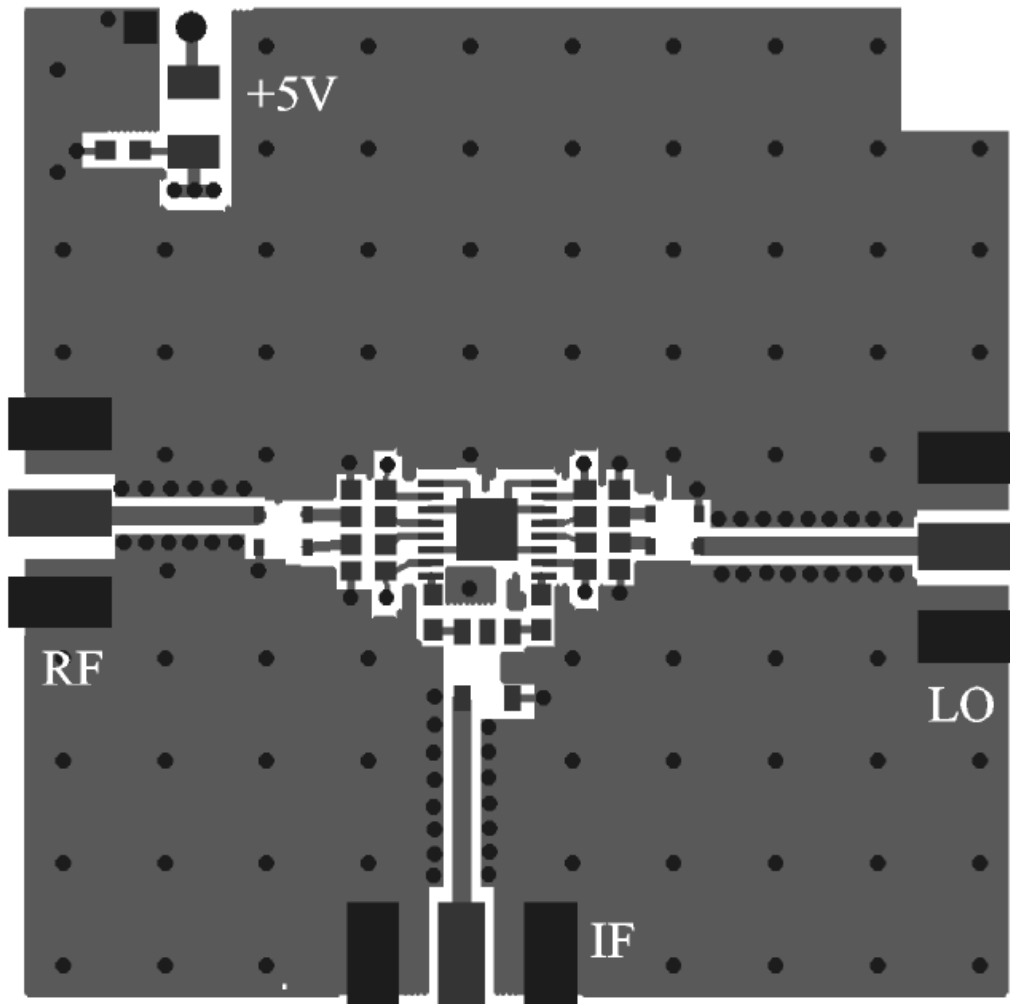
## Bill of Material of Demo Board

| Parameters                 | Test Conditions       | Pin                | Symbol        | Min.   | Typ.         |
|----------------------------|-----------------------|--------------------|---------------|--------|--------------|
| Highly linear active mixer |                       | Atmel              | ATR0785       |        | 16-pin TSSOP |
| Capacitor                  | C7, C9                |                    |               | 100 pF | 0603         |
| Capacitor                  | C1, C3, C20, C21, C30 |                    |               | 27 pF  | 0603         |
| Capacitor                  | C11, C12              |                    |               | 22 pF  | 0603         |
| Capacitor                  | C4, C5                |                    |               | 5.6 pF | 0603         |
| Inductor                   | Lfil                  | Würth Elektronik   | 74476401      | 1 µH   | 1210         |
| Inductor                   | L1                    | TOKO               | LL1608-FS39NJ | 39 nH  | 0603         |
| Transformer                | T9; T11               | Panasonic          | EHF-FD1618    |        |              |
| Transformer                | T2                    | Mini-Circuits®     | TC1-1         |        |              |
| RF connector               |                       | Johnson Components | 142-0701-851  |        | SMA          |

Note: 1. Other sizes are possible.

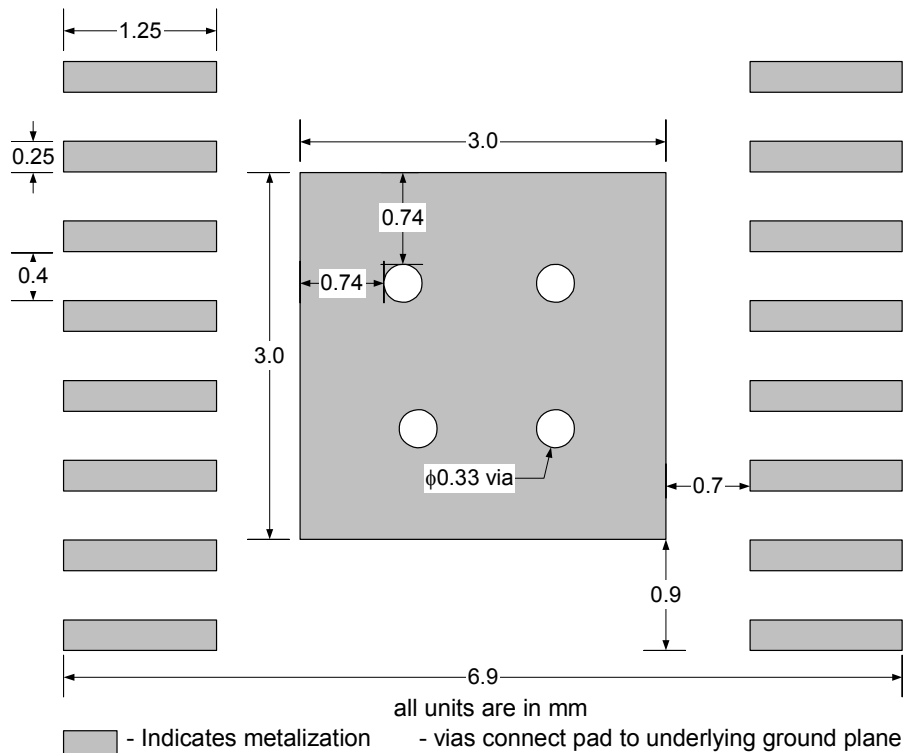


Figure 13. Demo Test Board



## Recommended Package Footprint

- Notes:
1. Only ground signal traces are allowed directly under the package.
  2. Primary dimensions are in millimeter alternate dimensions are in inches.



Remark: Heatslug must be soldered to GND!

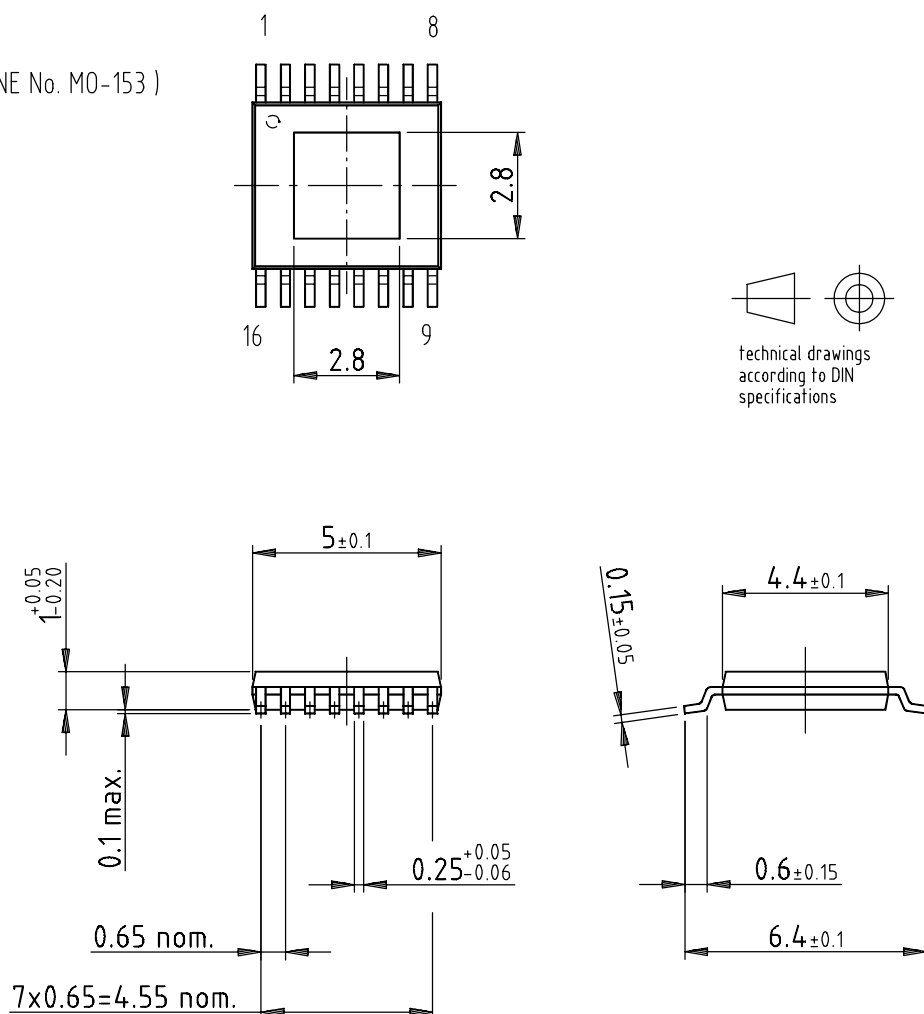
Plugging of the ground vias under the heat slug is also recommended to avoid soldering problems.

## Ordering Information

| Extended Type Number | Package | Remarks         |
|----------------------|---------|-----------------|
| ATR0785              | TSSOP16 | 5.0 mm × 6.4 mm |

## Package Information

Package: SSOP16  
( acc. JEDEC SMALL OUTLINE No. MO-153 )  
Dimensions in mm



Drawing-No.: 6.543-5079.01-4  
Issue: 1; 10.07.01



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